


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/17/9977	
1.3 Title of PCN	Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in UFQFPN 5x5 & 7x7 packages	
1.4 Product Category	UFQFPN 5x5 and 7x7 packaged products	
1.5 Issue date	2017-02-17	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Daniel COLONNA
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer...)	Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)

4. Description of change

	Old	New
4.1 Description	Current location : Stats ChipPAC Shanghai China (SCC)	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. See more information on PCN 9977 – Additional information document attached.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Change lead shape : with neck design. See in PCN 9977 – Additional information document attached. No change in fit, function, reliability or process ability.	

5. Reason / motivation for change

5.1 Motivation	Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only UFQFPN 5x5 and 7x7 packaged products.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability is described in PCN9977_Additional information attached document
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7. Timing / schedule

7.1 Date of qualification results	2017-05-26
7.2 Intended start of delivery	2017-06-26
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	9977 PCN9977_RERMCD1622- UQFN5x5_7x7 JSCC- MCD QA reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-02-17

9. Attachments (additional documentations)

9977 Public product.pdf
 9977 PCN9977_Additional information.pdf
 9977 PCN9977_RERMCD1622- UQFN5x5_7x7 JSCC- MCD QA reliability plan.pdf

10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F072C8U6	
	STM32F091CCU6	
	STM32F410C8U6	
	STM32F411CEU6	
	STM32L151C6U6	
	STM32L151C8U6	
	STM32L151C8U6	
	STM32L151CCU6	
	STM32L152C8U6	
	STM32L152C8U6	
	STM32L433CCU6	
	STM32L443CCU6	
	STM8L151C8U6	
	STM8TL53C4U6	
	STM32F031K4U6	
	STM32F031K6U6	
	STM32F051K4U6	
	STM32F051K4U6TR	
	STM32F051K6U6	
	STM32F051K8U6	
	STM32F301K8U6	
	STM32F302K8U6	
	STM32L062K8U6	
	STM32L432K8U6	
	STM32L432KCU6	
	STM32L442KCU6	
	STM8L151K3U6	
	STM8L151K4U6	
	STM8L151K6U6	
	STM8L152K6U6	
	STM8S103K3U6	
	STM8S105K6U6A	
	STM32F413CGU6	
	STM32F413CHU6	
	STM8L101K3U6	
	STM8L152C8U6	
	STM8L152K4U6	
	STM8S903K3U6	



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in UFQFPN 5x5 & 7x7 packages

PCN Reference : MDG/17/9977

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM8L151C8U3	STM8TL53C4U6	STM32L151C8U6TR
STM32F101C8U6TR	STM32L152C8U6A	STM32L152C6U6A
STM32F071C8U6	STM32F410C8U6	STM32L152C8U6
STM32F401CCU6TR	STM32F042C6U6	STM32F411CEU6TR
STM32F078C8U6	STM8L151C8U6	STM32L151C8U6TR
STM32F091CCU7	STM32L151C8U6D	STM32F401C8U6
STM32F101C8U6TR	STM32F091CCU6TR	STM8L152C4U6
STM32L151C6U6ATR	STM32L152C8U6	STM32L151C8U6
STM32F051C8U6TR	STM32F103C8U6	STM32F098CCU6
STM32F072C8U7	STM32F072C8U6TR	STM32L152C6U6
STM32F411CEU7	STM32L100C6U6A	STM32F042C6U7
STM32L433CCU6	STM32F101C8U6	STM8L151C4U6
STM32F071C8U7TR	STM32F401C8U7	STM32F071C8U7
STM32F410C8U6	STM32F051C8U7	STM8L151C6U3
STM32F051C4U6	STM32L151CCU6TR	STM32F103C8U6TR
STM32F071C8U6TR	STM32L443CCU6	STM32F051C8U6
STM32F072C8U6TR	STM32F411CEU6	STM32F051C6U6
STM32L151C8U6A	STM32F091C8U6	STM32F058C8U6
STM32L152C8U6A	STM32F401C8U6TR	STM32F072C8U6
STM32F072C8U6	STM32F048C6U6	STM8L152C6U3
STM32L100C6U6	STM32F401C8U6	STM32F401C8U6TR
STM32L152CCU6	STM32F101C8U6	STM32F411CCU6TR
STM32F091CCU6	STM32F401CCU6	STM32L151C6U6TR
STM32L151C6U6	STM32F401CEU6	STM32F103C6U6A
STM32F048C6U6TR	STM8L151C4U6TR	STM32L151CCU6
STM8L151C8U6TR	STM8L152C6U6	STM8L151C6U6
STM32L100C6U6TR	STM8L151C6U6TR	STM32L100C6U6ATR
STM8L152C8U6	STM32L151C8U6A	STM32L151C8U6
STM32L151C6U6A	STM32F051K6U6	STM32F302K8U6TR
STM32F051K8U7TR	STM32L051K8U6TR	STM32F302K8U6
STM8S105K6U3A	STM8S103K3U6	STM32L011K3U6
STM8S105K6U6A	STM32L031K6U6TR	STM32L052K8U6D
STM8S103K3U6TR	STM8S105K4U6A	STM32L442KCU6
STM32F051K6U6TR	STM32L052K8U3	STM32L051K6U6
STM32F031K6U7	STM32F051K4U6TR	STM32F031K6U6



Public Products List

STM32L052K8U6TR	STM32L432KCU6	STM32L071KZU3
STM32F031K4U6	STM32F042K6U6	STM32F301K8U7
STM32L052K6U6TR	STM8L151K4U6TR	STM32F042K6U7
STM32F301K6U6	STM32F051K4U7	STM32L071K8U6
STM8S903K3U6TR	STM32L031K4U6	STM32F301K6U7
STM32L041K6U7	STM8L151K6U6	STM8S903K3U3
STM32L011K4U6	STM32L052K6U6	STM32L011K4U3
STM8L101K3U6	STM8L151K3U6	STM8L152K4U6
STM32L072KBU7	STM32F302K6U6	STM32F042K4U6
STM32F302K8U7	STM32L041K6U6D	STM32L031K4U6TR
STM32F051K4U7TR	STM32F051K6U7TR	STM32L062K8U6
STM32F051K8U7	STM8L152K6U6TR	STM32L031K6U7
STM8S105K6U6ATR	STM32L051K8U7TR	STM8L101K3U6TR
STM8L151K3U3	STM32L072KBU6	STM32F301K8U7TR
STM32F318K8U6	STM32F031K4U6TR	STM32F038K6U6
STM8S903K3U3TR	STM32L082KBU6	STM32L051K8U6DTR
STM8S105K4U6ATR	STM32L071KBU6	STM8S105K4U3A
STM32F051K6U7	STM32F051K8U6TR	STM32L072KZU6
STM32L051K8U7	STM32F301K6U6TR	STM8L151K4U6
STM8L151K2U6	STM32L081KZU6	STM32L071K8U3
STM32F051K8U6	STM32L052K8U6DTR	STM8L151K6U3
STM8L152K6U6	STM32F031K6U6TR	STM8L151K3U3TR
STM32L041K6U6	STM32L041K6U6TR	STM32L071KBU3
STM32L052K8U3TR	STM32L051K8U6	STM32F318K8U7
STM32L082KZU6	STM8L151K6U6TR	STM32L031K6U6
STM32F301K8U6TR	STM32L051K6U6TR	STM32L052K8U6
STM32F301K8U6	STM8S903K3U6	STM32L051K8U3
STM32L071KZU6	STM32F051K4U6	STM32F072CBU7TR
STM32F072CBU7		



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